

PCB MANUFACTURING SPECIFICATIONS

"LTK-HALL 2019"

SPECIFICATIONS

NOTE #	NOTE
1	ALL SPECIFICATIONS REFERENCED ARE OF THE REVISION SPECIFIED IN THE TITLE BLOCK
2	SUPPLIER SHALL NOT MODIFY THE DESIGN OR APPROVED STACK-UP WITHOUT WRITTEN PERMISSION
3	ALL MATERIALS SHALL BE RoHS COMPLIANT AND FINAL PRODUCT SHALL BE ACCEPTABLE TO USE IN RoHS ASSEMBLY. RoHS LOGO SHALL BE MARKED IN SILKSCREEN INK NEAR BY THE SUPPLIER.
4	COPPER FOIL: REFER TO LAYER STACK LEGEND FOR Cu THICKNESS DETAILS. ALL Cu THICKNESSES ARE FINISHED AND INCLUDE BASE FOIL PLUS Cu PLATING ON PLATED LAYERS
5	ELECTRICAL TEST: ALL PRINTED CIRCUITS SHALL BE 100% ELECTRICALLY TESTED FOR OPENS/SHORTS USING PROVIDED NETLIST. REJECTED PRINTED BOARDS MUST BE CLEARLY MARKED WITH NON-CONDUCTIVE, PERMANENT INK.
6	MARKINGS: VENDOR MARKING AND DATE/LOT CODES SHALL BE LOCATED ON THE BOARD IN THE RESERVED AREA AS SPECIFIED IN THE GERBER LAYER "PCBM_NOTES" BY THE TEXT "YOU CAN PLACE MARKINGS HERE".
7	MARKINGS: THE SIDE ONTO WHICH PLACE THE MARKINGS IS AT THE SUPPLIER DISCRESSION UNLESS OTHERWISE NOTED ONTO THE LAYER "PCBM_NOTES"
8	SUPPLIER SHALL CHECK PCBM_NOTES LAYER BEFORE ASKING FOR CLARIFICATIONS
9	MANUFACTURE TENTED/PLUGGED VIAS AS SPECIFIED IN THE GERBER FILES

SPECIFICATIONS

LENGHT	117.50
WIDTH	100
LAYERS	4
MATERIAL	FR-4
MATERIAL MIN TG	130-140
TRACK WIDTH/CLEARANCE	8 mils / 8 mils
THICKNESS	1.6mm
COPPER THICKNESS	35um (1oz)
SOLDERMASK	YES, TOP AND BOTTOM
SOLDERMASK COLOR	RED
SILKSCREEN	YES, TOP AND BOTTOM
SILKSCREEN COLOR	WHITE
SURFACE FINISH	HASL LEAD FREE
GOLD FINGERS	NO
CHAMFERING	NO
IMPEDANCE CONTROL	NO
HALF-CUT/CASTELLATED HOLES	NO
BURIED/BLIND VIAS	NO
VIAS FILLED WITH RESIN	NO
CARBON MASK	NO
COUNTERSINKS/COUNTERBORES	NO
Z-AXIS MILLING	NO
PEELABLE SOLDERMASK	NO

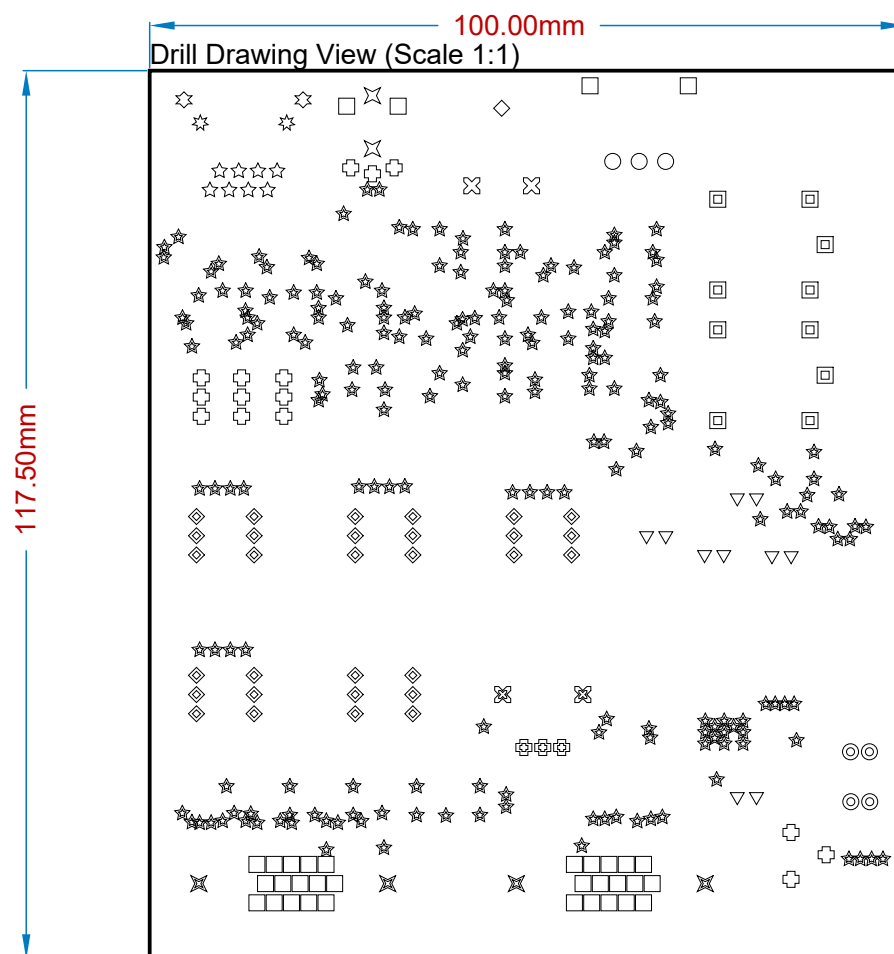
Layer Stack Legend	Material	Layer	Thickness	Dielectric Material	Type	Gerber
		Top Overlay			Legend	GTO
	Surface Material	Top Solder	0.03mm	SM-001	Solder Mask	GTS
	Lead-Free	Top Surface Finish	0.02mm		Surface Finish	
	CF-004	Top Layer	0.04mm		Signal	GTL
	Prepreg		0.13mm	PP-017	Dielectric	
	Prepreg		0.13mm	PP-017	Dielectric	
	CF-004	Int1 (GND)	0.04mm		Signal	G1
	Core		0.71mm	Core-039	Dielectric	
	CF-004	Int2 (PWR)	0.04mm		Signal	G2
	Prepreg		0.13mm	PP-017	Dielectric	
	Prepreg		0.13mm	PP-017	Dielectric	
	CF-004	Bottom Layer	0.04mm		Signal	GBL
	Lead-Free	Bottom Surface Finish	0.02mm		Surface Finish	
	Surface Material	Bottom Solder	0.03mm	SM-001	Solder Mask	GBS
		Bottom Overlay			Legend	GBO

Total thickness: 1.46mm

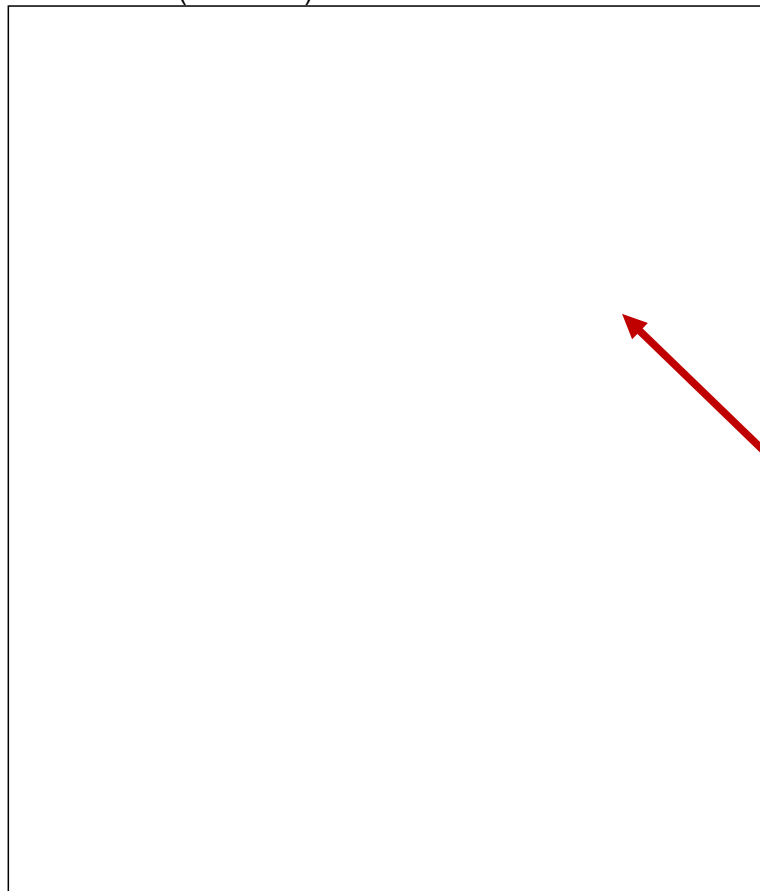
Board outline (Scale 1:1)



100.00mm
Drill Drawing View (Scale 1:1)



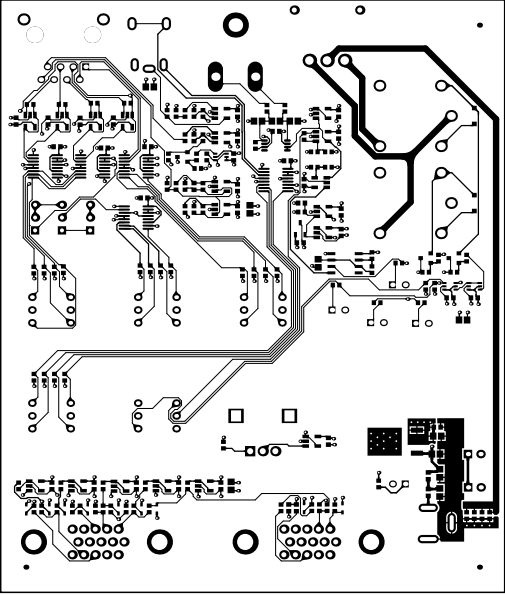
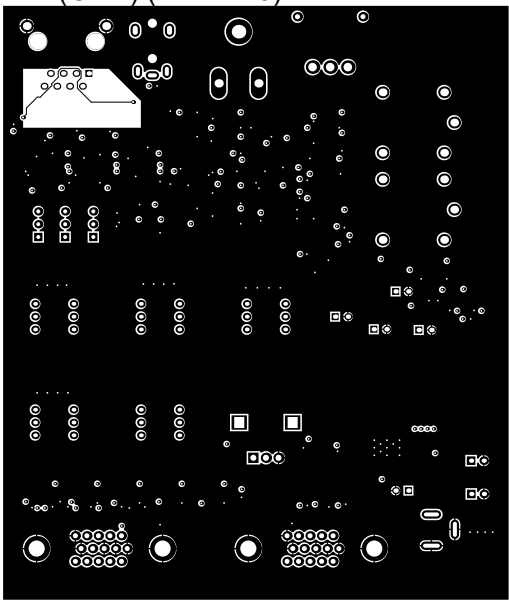
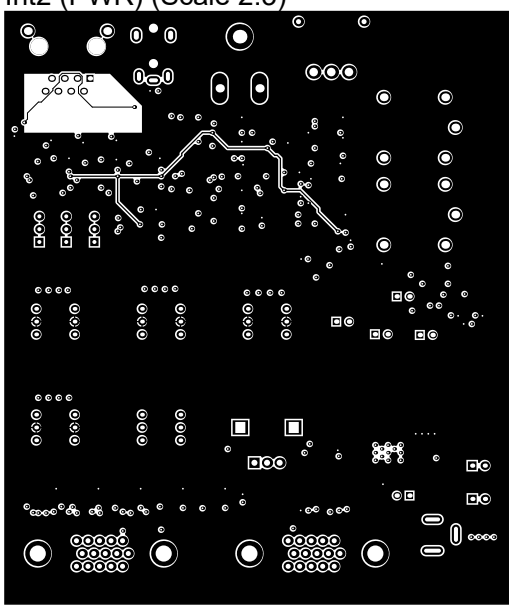
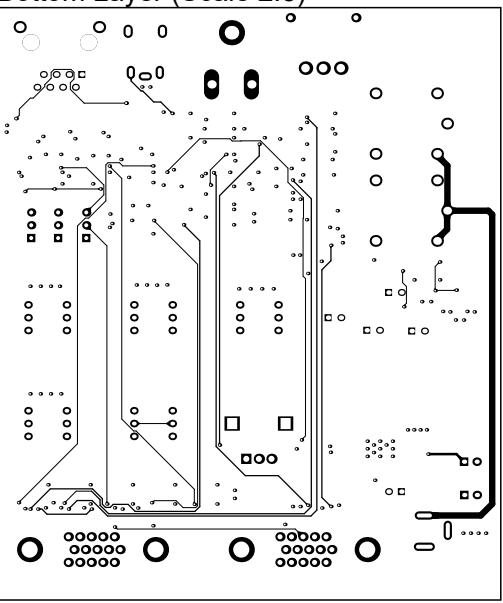
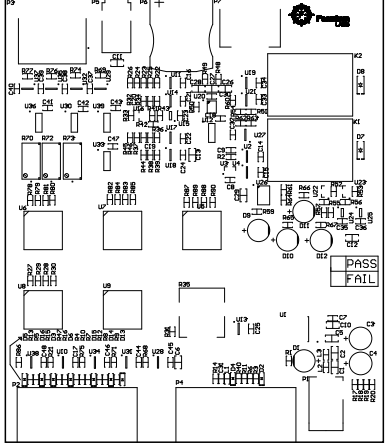
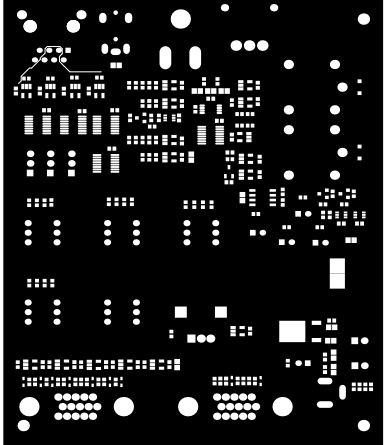
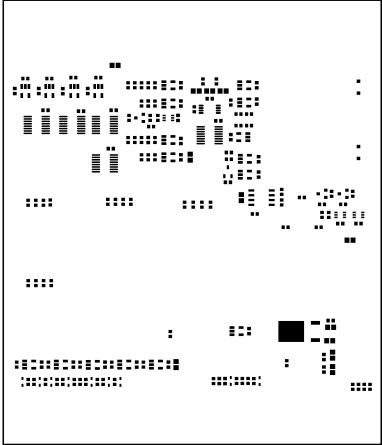
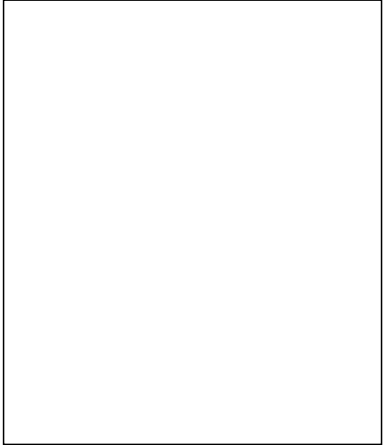
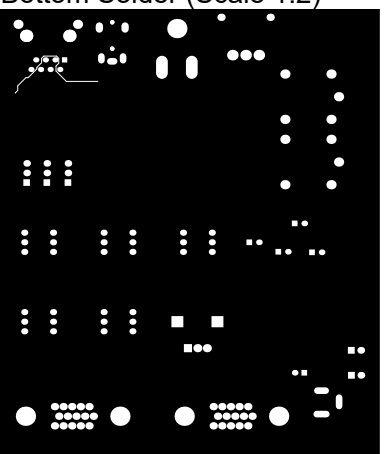
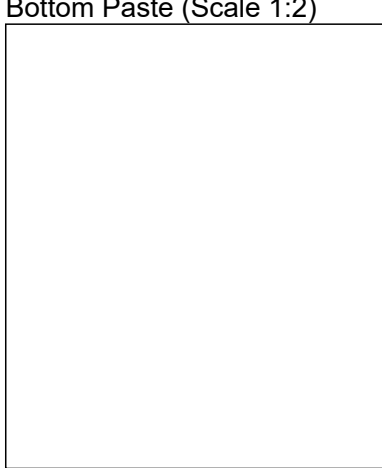
PCBM Notes (Scale 1:1)



ALWAYS CAREFULLY READ THE INDICATIONS ON THIS LAYER

Drill Table

Symbol	Count	Hole Size	Plated	Hole Tolerance
☆	213	0.35mm	Plated	
◇	30	0.76mm	Plated	
⊕	15	0.80mm	Plated	
◎	4	0.85mm	Plated	
▽	10	0.89mm	Plated	
☆	8	0.89mm	Plated	
□	34	1.00mm	Plated	
✕	2	1.20mm	Non-Plated	
⊗	3	1.20mm	Plated	
▣	10	1.55mm	Plated	
☆	2	1.57mm	Plated	
✕	2	1.65mm	Plated	
○	3	1.70mm	Plated	
⊗	2	2.20mm	Plated	
◇	1	2.70mm	Plated	
✕	4	3.20mm	Plated	
☆	2	3.25mm	Non-Plated	
	345 Total			

	A	B	C	D	E	F	G	H	
1	<div>Top Layer (Scale 2:3)</div> 								1
2	<div>Int1 (GND) (Scale 2:3)</div>  <div>Int2 (PWR) (Scale 2:3)</div>  <div>Bottom Layer (Scale 2:3)</div> 								2
3	<div>Top Overlay (Scale 1:2)</div>  <div>Top Solder (Scale 1:2)</div>  <div>Top Paste (Scale 1:2)</div> 								3
4	<div>Bottom Overlay (Scale 1:2)</div>  <div>Bottom Solder (Scale 1:2)</div>  <div>Bottom Paste (Scale 1:2)</div> 								4
5									5
6									6
	A	B	C	D	E	F	G	H	